Build Up HDI (Standard)

HDI08_1+6+1_1,40_17.5_engl

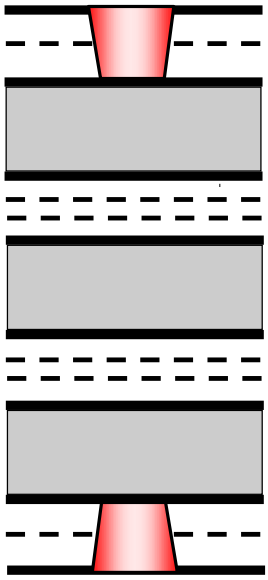
8 - Layers

Core: 0,30 mm Cu 17/17 µm

WE-Articel No.: **1 + 6 + 1**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	66	
	2			17,5 µm		16	
			0,300 mm			300	
	3			17,5 µm		16	
					2 x 1080	134	
	4			17,5 µm		16	
			0,300 mm			300	
	5			17,5 µm		16	
					2 x 1080	134	
	6			17,5 µm		16	
			0,300 mm			300	
	7			17,5 µm		16	
					1 x 1080	66	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness:						1420	

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,40**	+/-	0,11	mm			Date:	Engineer:
thickness with electro plated Cu:	1,49	+/-	0,14	mm				
total thickness with soldermask	1,55	+/-	0,16	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision		
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	page:	6+